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PATENT
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: **Yuji ONO et al.**

Serial No.: **Not Yet Assigned**

Filed: **August 29, 2001**

For: **SINGLE WAFER TYPE SUBSTRATE CLEANING METHOD AND APPARATUS**

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

August 29, 2001

Sir:

Prior to the calculation of the filing fees of the above application, please amend the application as follows:

IN THE CLAIMS:

Please amend claims 10 and 12-14 as follows:

10. (Amended) The single wafer type substrate cleaning apparatus according to Claim 5, wherein the gas injection section is movable between a use position where it cooperates with the cleaning chamber and a standby position where it does not interfere with the chemical fluid supply means.

12. (Amended) The single wafer type substrate cleaning apparatus according to any of Claims 4 to 10, wherein the cleaning chamber is designed in such manner that the inner peripheral portion of each annular treatment bath does not contact the outer periphery of the wafer supporting